TOSHIBA SCHOTTKY BARRIER RECTIFIER SCHOTTKY BARRIER TYPE

U1FWJ44N

HIGH SPEED RECTIFIER APPLICATIONS

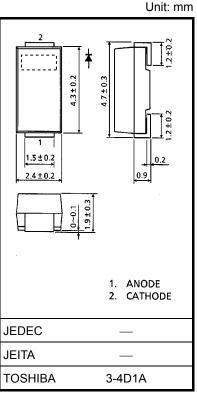
ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	30	V
Average Forward Current	I _{F (AV)}	1.0	Α
Peak One Cycle Surge Forward Current (Non-Repetitive)	I _{FSM}	25 (50Hz)	Α
Junction Temparature	Tj	-40~125	°C
Storage Temparature Range	T _{stg}	-40~125	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling

Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



Weight: 0.06 g (typ.)

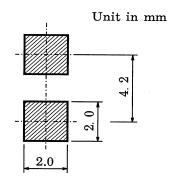
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	V_{FM}	I _{FM} = 1.0A	_	_	0.37	V
Repetitive Peak Reverse Current	I _{RRM}	V _{RRM} = 30V	_	_	1.5	mA
Junction Capacitance	Cj	V _R = 10V, f = 1MHz	_	62	_	pF

MARKING

Abbreviation Code	Part No.			
1F	U1FWJ44N			

STANDARD SOLDERING PAD



Handling Precaution

Schottky barrier diodes have reverse current characteristic compared to the other diodes.

There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage. This device is VF-IRRM trade-off type, lower VF higher IRRM; therefore, thermal runaway might occur when voltage is applied. Please take forward and reverse loss into consideration during design.

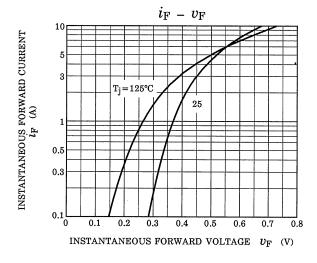
The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

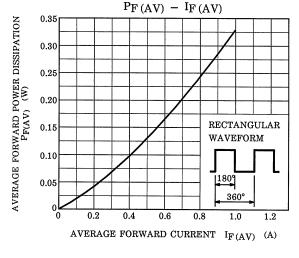
- VRRM: Use this rating with reference to the above. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
- IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV) and T_j be below 100°C. When using this device, take the margin into consideration by using an allowable Tamax-IF(AV) curve.
- IFSM: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.
- T_j : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_i of below 100°C.

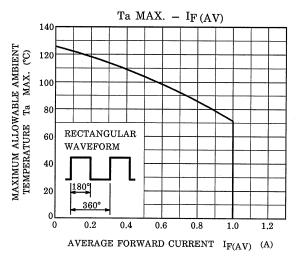
Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, please design a circuit board and a soldering land size to match the appropriate thermal resistance value.

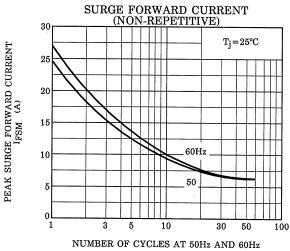
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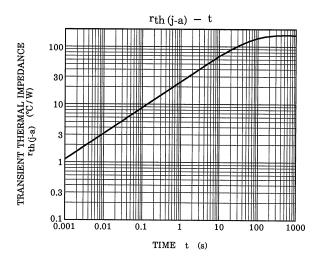
Please refer to the Rectifiers databook for further information.

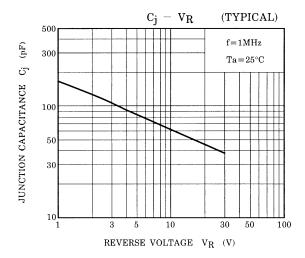


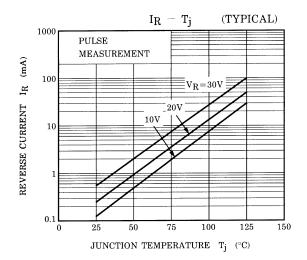


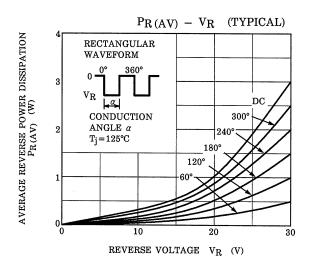












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RESTRICTIONS ON PRODUCT USE

20070701-EN

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- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
 In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
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